ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Composition © Copyright 2005. IPC, Banı international and Pan-Americ	nockburn, Illinois. A	Il rights reserved u ntions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the s encompass	substances es all lowe	within the manufacture level materials for v	rer listed i which the r	item. Note: i nanufacturer	f the item is an as r has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ   http://www.ipc.org/IPC-175x Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					ials and M	als and Mfg Information			
Supplier Information													
Company name* Company unique ID			DID Unic			Unique ID Authority				Response Date*			
ısemi									2023-06-08				
Contact Name	Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	t-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
horized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr	Item Number	Mfr Item Name			Effective Dat	e Version	1	Manufacturing Site		Weight*	UOM	Unit Type	
NC	CP1117ST12T3G ANA LOW DIF		800MA POS RE	EG	2023-06-08			MY1		108.86	mg	Each	
Manufacturing Proccess Information					•								
Terminal Plating / Grid Array Material	Terminal Base Alloy		J-STD-020 MSL	Rating	Peak Pro	rocess Body Temperature Max Time at Peak		k Tempera	Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alloy 1			1		260		С	30	secor	nds 3			
Comments													
level 1 - maximum time at peak temperature durin	ng soldering is 10-3	0 seconds											
For more information regarding material composi	ition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl e (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Die Attach	0.74	mg		Epoxy resin	proprietary data		0.0185	mg
			Supplier	Silver (Ag)	7440-22-4		0.6253	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0185	mg
			Supplier	Inorganic filler	Proprietary Data		0.0185	mg
			Supplier	Dicyandiamine	461-58-5		0.0037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0555	mg
Lead Frame	37.17	mg	Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	62.4	mg		Epoxy resin	proprietary data		3.12	mg
			Supplier	Phenolic Resin	Proprietary Data		3.12	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.248	mg
			Supplier	Carbon Black (C)	1333-86-4		0.312	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		54.6	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg